



MARCH FlexTRAK® – SHS

Industry-Leading Throughput and Reliability

Built upon MARCH's patented plasma technology, the FlexTRAK®-SHS is our latest fully automated plasma system incorporating a high-capacity F3-S chamber, to provide high uniformity and increased productivity. The chamber architecture remains the same as the smaller FlexTRAK® platform, providing a seamless transition between chambers as production demands more capacity.

A FlexTRAK-HS variant with standard F3 chamber is also available for customers who do not require the capacity of the F3-S chamber.

The FlexTRAK®-SHS provides:

Industry-Leading Throughput

- Large capacity F3-S process chamber
- Simultaneous strip buffering and processing
- Advanced automation and magazine splitting capabilities

New Product Development

- Advanced material handling
- Ability to accommodate increasingly larger strip sizes
- Sophisticated jam detection

Application Flexibility

- Plasma chamber effectiveness
- Configurable process chamber
- Versatile treatment modes

Key Applications

- Pre-wire bond plasma treatment on semiconductor package substrates and lead frames
- Pre-underfill plasma treatment on flip chip packages
- Pre-mold plasma treatment on semiconductor package substrates and lead frames
- Plasma treatment of semiconductor package substrates and lead frames for improved adhesion
- Removal/reduction of oxidation on lead frames

Specifications

Enclosure Dimensions	W x D x H – Footprint	2314 W x 1935 D x 1787 H mm (2293 H mm with light tower) 91.1 W x 76.2 D x 70.5 H in (90.3 H in with light tower)
	Net Weight	1305 kg (2,871 lbs)
	Effective Footprint –Clearances	All sides – 700 mm (27.6 in)
Chamber	Volume	F3-S chamber: 9.6 liters (585 in ³) F3 chamber: 5.5 liters (338 in ³)
Electrodes	Powered Electrode Dimensions	F3-S chamber: 305 W x 610 D mm / 12 W x 24 D in F3 chamber: 305 W x 305 D mm / 12 W x 12 D in
RF Power	Standard Wattage	F3-S chamber: 1000 W F3 chamber: 600 W
	Frequency	13.56 MHz
Gas Control	Maximum Number of MFCs	4
Control System	Interface	EPC with PC Based Touch Screen Interface
Remote Interface	Communications	SECS/GEM, Remote HMI
Vacuum Pump	Standard Dry Pump	16 CFM, Variable Frequency Drive
	Optional Wet Vacuum Pump	19.5 CFM at 60Hz Wet Pump with Oil Mist Eliminator
	Optional Purged Dry Pump	16 CFM, Variable Frequency Drive
	N2 Purged Pump Flow	2 SLM
Facilities	Power Supply	220V, 40A, 50/60 Hz, Single Phase, 12 AWG, 3-Wire
	Process Gas Fitting Size & Type	.25-in OD Swagelok Compression
	Process Gas Purity	Industrial grade or better
	Process Gas Pressure	Regulated from .69 bar (10 psig) min to 1.4 bar (20 psig) max
	Purge Gas Fitting Size & Type	.25-in OD Swagelok Compression
	Purge Gas Purity	Industrial grade Nitrogen or CDA
	Purge Gas Pressure	Regulated from 5.5 bar (80 psig) min to 6.9 bar (100 psig) max
	Handler Pneumatic Valves Fitting Size & Type	10 mm push-in fitting
	Pneumatic Gas Purity	CDA, Oil Free, Dewpoint <=7 °C /45 °F, Particulate Size <5 micron
	Handler Pneumatic Gas Pressure	4.5 – 6 bar (65 – 87 psig)
	Handler Exhaust Fitting	12 mm push-in fitting
	Compliance	Certifications
Ancillary Equipment	Nitrogen Generator (option)	Necessary for Purge Gas Requirements
	Chiller (option)	Required When Configured with Cooled Electrode
	Hydrogen Kit (option)	Allows System to Use Hydrogen Gas for Processing
	Scrubber (option)	Intended for Fluorinated Operations on the System
Shipping	Gross Weight	1505 kg
	Number of Packages	1
	Packing Conforms to ISPM 15	Yes

For more information, speak with your Nordson representative or contact your Nordson regional office.

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